

Technical Data Sheet

MODEL NO: Q350NNZ4 1206 SMD With Inner Lens

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP/GaAs	Yellow	Water transparent

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

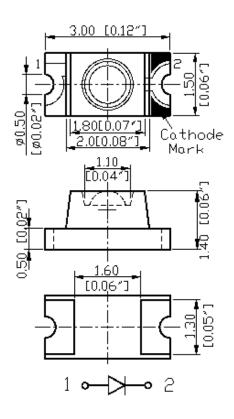
Parameter	Test	Value			- Unit	
	Condition	Symbol dition	Min	Тур	Max	Uilli
Spectral half bandwidth	IF=20mA	Δλ		18		nm
Dominant wavelength	IF=20mA	λD	585	590	595	nm
Forward voltage	IF=20mA	VF	1.8		2.4	V
Luminous intensity	IF=20mA	lv	800	1400	2500	mcd
Viewing angle at 50% lv	IF=10mA	2 <i>0</i> 1/2		40		Deg
Reverse current	V _R =5V	l _R			10	μΑ



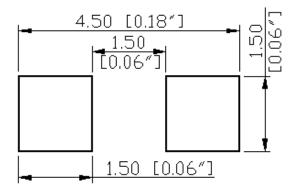
Absolute Maximum Ratings(Ta=25℃)

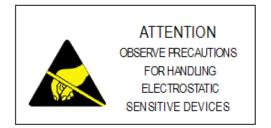
Parameter	Symbol	Value	Unit
Power dissipation	Pd	75	mW
Forward current	lF	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	lfP	125	mA

PACKAGING DIMENSIONS (mm):



RECOMMEND PAD LAYOUT





NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ±0.1mm (0.004inch) unless otherwise noted.

Typical Electro-Optical Characteristics Curve:

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Fig 1. Forward Current vs. Forward Voltage

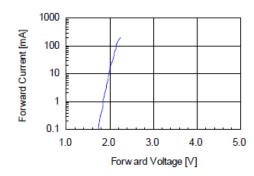


Fig 2. Relative Intensity vs. Forward Current

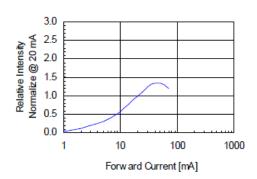


Fig 3. Forward Voltage vs. Temperature

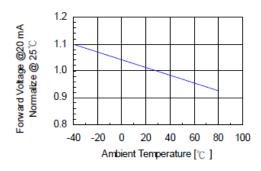


Fig 4. Relative Intensity vs. Temperature

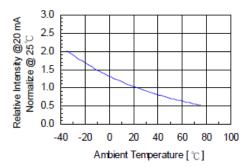
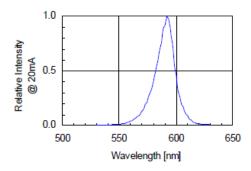


Fig 5. Relative Intensity vs. Wavelength



Precautions For Use:

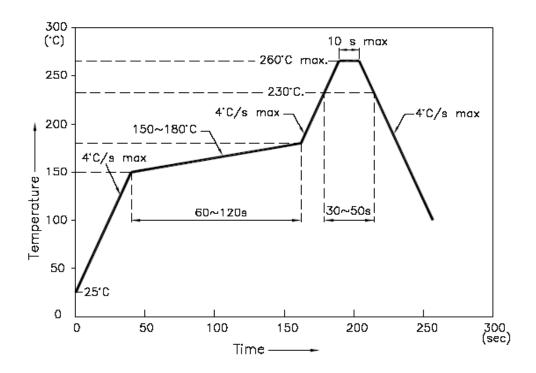
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

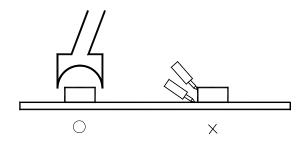


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

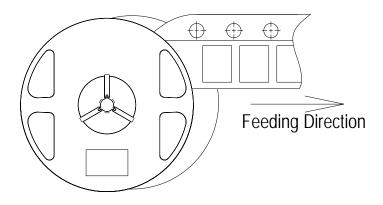
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



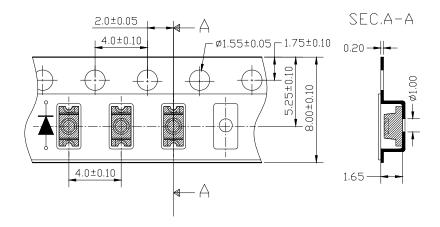
■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.



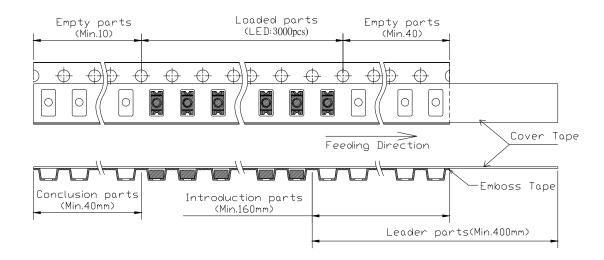
■Feeding Direction



■Dimensions of Tape (Unit: mm)



■Arrangement of Tape



■Note

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two